Israel Section

Section Vitality
The last Section elections took place in 2.2020.

Students
No new Student Branches (SB) in our Section, since the last meeting reporting (Oct 2020). The Section activities addressed to Students and Young Professionals are listed at the IEEE Vtools reports.

Affinity Groups
YP LM and WIE were active in 2020, as was reported at IEEE Vtools.

Chapters
We established new chapter (EP) and renew inactive chapter and affiliated group with new chairs (CS, WIE).

Industry
In 2020/2021 we have organized IEEE COMCAS2021 to be held on 1-3 November 2021. IEEE COMCAS 2019 held in 4-6 Nov. 2019 in Tel Aviv was most successful, with over 1900 attendees, most of them from the Industry and large Industry exhibition (100 booths). We had 216 presentations and 72 top level invited speakers. We organized successful IEEE SA workshops (with Industry presentations, (January 2020), Bio Medical Engineering Conference in Haifa in 3.2020, Antennas Symposium in TAU (Tel Aviv) in 3.2020, EMC Conference (Virtual) (2020) and more, all with Academia and Industry speakers and participants. R8 can help with advertising and with top level speakers.

Planned activities
We established new chapter (EP) and renew inactive chapters with new chairs (CS, WIE). We plan to increase technical and social activities of chapters and affiliated groups, and discussed with IEEE on corporate membership.

I wish to update our website. I migrated recently the site to the IEEE server and have IEEE IT technical support. Plan to have local webmaster and update the content of the website.

How Region 8 can be of help to your Section, members, and activities
IEEE R8 helps when needed.

Any other issues of interest
No.
On behalf of the IEEE COMCAS 2021 Steering Committee, it is our pleasure to launch the 8th International IEEE Conference on Microwaves, Communications, Antennas, and Electronic Systems (IEEE COMCAS 2021).

In 2021 the International IEEE COMCAS will continue to evolve and provide an advanced multidisciplinary forum for the exchange of ideas, research results, and industry experience in a range of key areas i.e., communications and sensors, antennas, biomedical engineering, RF and Microwave devices and circuits, thermal management and electronic packaging, signal processing and imaging, as well as radar, acoustics and Microwave system engineering. In its entirety the event includes a technical program, industry exhibits, and guest presentations from global experts on recent academic and industry advancements.

Held from 1-3 November 2021 in Tel Aviv Israel, at the David Intercontinental Hotel by the Mediterranean Sea; IEEE COMCAS is a biennial series tailored to maximize networking, support the candid exchange of ideas, and develop a range of enduring opportunities.

Our Technical Program is paired with a Technical Exhibition that offers companies and agencies a unique opportunity to visit Israel, present relevant products and quality services, and pursue key networking opportunities. Attendees can take part and engage with new contacts, create business opportunities and solidify contracts for the future.

IEEE COMCAS 2019 was our greatest success to date with near 1900 attendees, over 240 lectures in 88 sessions, alongside participants from 39 countries, and exhibitors from more than 100 industry vendors. Following a year of great transformation, we are confident that IEEE COMCAS 2021 will transcend our expectations on both a professional and personal level.

We invite you to join us in Tel Aviv on 1-3 November to take an active part in IEEE COMCAS 2021 and be a part of its success.

**IMPORTANT DATES**

- **May 3, 2021**: Abstract/Paper Submission for initial reviews
- **June 1, 2021**: Submission of proposals for workshops, short courses and tutorials
- **July 22, 2021**: Accept/revise/reject notifications sent to authors
- **September 1, 2021**: Final revised manuscripts submission deadline
IEEE COMCAS 2021 will feature invited talks, technical lectures and short courses given by distinguished international experts. Additional suggestions for workshops and short courses will be considered. For suggestions, please provide a short description of your proposal, including a list of potential talks and speakers, indicating which have already confirmed. Proposals should be submitted to Vadim.Issakov@ovgu.de

GRANTS & AWARDS

The Mini-Circuits Harvey Kaylie Best Paper & Best Student Paper Awards
Awards (1,800 USD each) will be granted on the third conference day.

The European Microwave Association (EuMA) Student Paper Awards
Two awards (1,000 EUR each) will be granted on the third conference day.

Student/Young Scientist Travel Grants
IEEE COMCAS 2021 encourages participation of young scientists to present papers at the conference. Several travel grants will be provided on a competitive basis. Each grant is up to 500 USD.

SPECIAL EVENTS

Young Professionals: Entrepreneurship in Semiconductors
IEEE COMCAS 2021 will again host the popular innovation session by IEEE YP and the ACRC - Advanced Circuits Research Center of the Technion. The special session will feature successful technology and innovation leaders of the Israeli high-tech industry. A perfect place to broaden your professional network while enjoying Tel Aviv.

Women in Engineering (WIE)
Historically, women represent only 10–20% of the overall engineering work force. So how can one make engineering more attractive to young women? How can one increase the number of women in engineering? To seek for the answers, join us for the WIE event! Our speakers are prominent women in electronics and electro-optics engineering who will share and discuss their career challenges and triumphs.

Your Career in Microwaves
Executive workshops on how to start-up your career in the microwave industry held by leading career consultants and industry executives.

SIGHTSEEING OPPORTUNITIES

In launching the 2021 event we would also like to welcome you to the sunshine of the eastern Mediterranean, in Tel Aviv. As a cosmopolitan city of stunning views and endless innovation, Tel Aviv is a center that resonates with an energized atmosphere, streets of storied history, and an internationally recognized nightlife.

Depart from Tel Aviv to discover the whole of Israel—sea and coral reefs, desert and mountains, holy and historic sites of three religions, Israel offers you endless experiences in just a short drive away. Your unique experiences may include floating in the Dead Sea, sleeping under a Bedouin tent, visiting the Holy Sepulcher, walking in the ancient Western Wall tunnels – name your dream.
## TECHNICAL PAPERS AND ABSTRACTS

IEEE COMCAS offers seven technical tracks welcoming high quality research, tutorial, and application papers or abstracts. All submitted papers and abstracts will be peer reviewed. Accepted ones will be published in the IEEE COMCAS 2021 Proceedings. Presented full papers will be submitted for inclusion in IEEE Xplore®.

## LIST OF TOPICS

### Communications and Sensors

- Beyond 5G – Systems & Technologies
- AI, Machine Learning, Deep Learning in Communications and Sensors
- Big Data in Communication Networks
- MIMO & Space-Time Coding Technologies
- 5G systems & Millimeter Wave Propagation
- Cognitive Radio & Spectral Sharing
- Communications Security
- First Responder/Military Communications
- Green Communication
- Internet of Things
- Long Range Low Power Networks
- Micro/Pico/Femtocell Devices and Systems
- Modulation & Signal Processing Technologies
- On-Body and Short Range Communications
- Radio over Fiber & Optical/Wireless Convergence
- Sensor Networks and Technologies
- Software-Defined Radio & Multiple Access

### Antennas, Propagation, and Scattering

- Antenna Theory and Design
- Smart Antennas, Beamforming and MIMO
- Wave Propagation and Channel Modeling
- Wave Scattering and RCS
- NanoEM, Plasmonics, and Applications
- Metamaterials, FSS and EBG
- EM Field Theory and Numerical Techniques
- EM Interference & Compatibility, SI
- Spectrum Management and Monitoring
- ELF, RF, μWave, mmW and THz Measurements

### Electronic Packaging & Thermal Management (P&TM)

- P&TM of Electronics on Device and PCB Levels
- Microelectronics P&TM on Chip Level
- P&TM of RF Devices
- P&TM of Photonics and Optics
- P&TM of Medical Devices
- Structural, Joining, and Coating Materials
- Destructive and Non-Destructive Testing
- Advanced Methods for Thermal Management
- Numerical Modeling of Thermal Management
- Reliability of Electronic Devices

### Biomedical Engineering

- Advances in MRI: Technology, Systems and Applications
- Medical RF, MW & MMW Applications and Devices
- Medical Imaging and Image Processing
- Acousto-Optic Technologies
- Novel Therapeutic Modalities
- Biomedical Systems and Applications
- Effects of RF and MW on Biological Tissues

### RF/MW Devices and Circuits, RFICs

- Solid-State Devices, RFICs
- μWave, mmW and Sub-mmW Circuits/Technologies
- Nano and THz Devices/Technologies
- Microwave Photonics
- Passive Components and Circuits
- Filters and Multiplexers
- Ferroelectrics, RF MEMS, MOEMS, and NEMS
- Active Devices and Circuits
- RF Power Amplifiers and Devices
- Tunable and Reconfigurable Circuits/Systems
- Analog/Digital/Mixed RF Circuits
- Circuit Theory, Modeling and Applications
- Interconnects, Packaging and MCM
- CAD Techniques for Devices and Circuits
- Emerging Technologies
- Internet of Things Devices

### Microwave Systems, Radar, Acoustics

- Aeronautical and Space Applications
- RFID Devices/Systems/Applications
- Automotive/Transportation Radar & Communications
- Environmentally Sensitive (“Green”) Design
- UWB and Multispectral Technologies & Systems
- Emerging System Architectures
- Modelling Techniques for RF Systems
- Radar Techniques, Systems and Applications
- Sonar Systems and Applications
- Wireless Power Transfer & Energy Harvesting
- Terahertz Systems
- AI, Machine Learning, Deep Learning in Microwave, Radar, and Acoustic Systems

### Signal Processing (SP) and Imaging

- Microwave Imaging and Tomography
- Acoustic/Sonar Imaging and Techniques
- Radar SP and Imaging, SAR, ATR
- MIMO SP for Radar
- Ground and Foliage Penetration Systems
- Signal Acquisition and Sensor Management
- DF, Emitter Location, Elint, Array Processing
- Target Detection, Identification and Tracking
- Data Fusion
- Time Domain and UWB SP
- AI, Machine Learning, Deep Learning in Signal and Image Processing

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To submit your paper and further information please scan the barcode

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